

Q-Series H-Pin Socket

Accelerated life testing solution



The Q-Series socket is available for mid to large package sizes. The Q-Series is a fully molded socket body and lid designed to meet the rigors of a wide variety of accelerated life testing applications.

The lid can be configured with or without a heatsink for precise thermal response and with the aid of design simulation air channels are optimized to maintain accurate temperature throughout testing.

This socket also uses the H-Pin™ contact technology providing wide RF performance capabilities and exceptional DC characteristics. The Q-Series socket checks all the boxes: high frequency, high current, high temperature, low inductance, and low loss. These features contribute to lower the cost of tests.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

Benefits

- Industry-proven design, in-house tooling, molding, and machining, with 100% automated assembly.
- Extensive catalog of components, configurable options
- H-Pin offers unmatched DC performance.

Feature options

- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Max component clearance under the DUT
- 2 or 3 plate systems
- High temperature materials for above 200°C applications

Q-Series socket specifications

Mechanical properties

- Pitch: ≥ 0.35 mm
- Package size:
 - LGA: 12 mm to 32 mm
 - BGA: 12 mm to 32 mm
- Pin count: 2000+
- Temperature: -55°C to 260°C

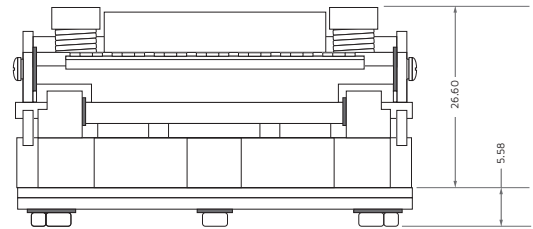
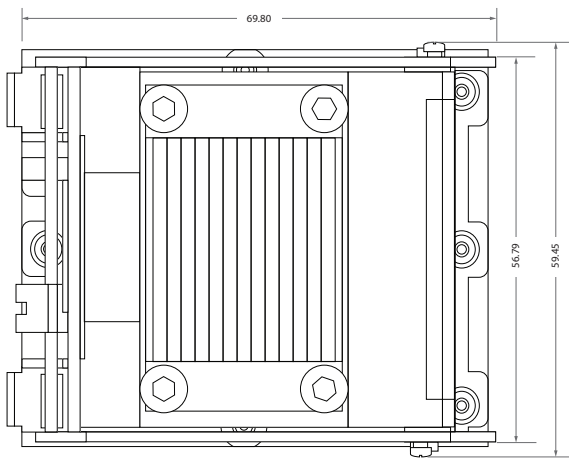
Electrical properties

- Contact resistance: $35\text{ m}\Omega$
- Current carrying capacity: up to 4 A

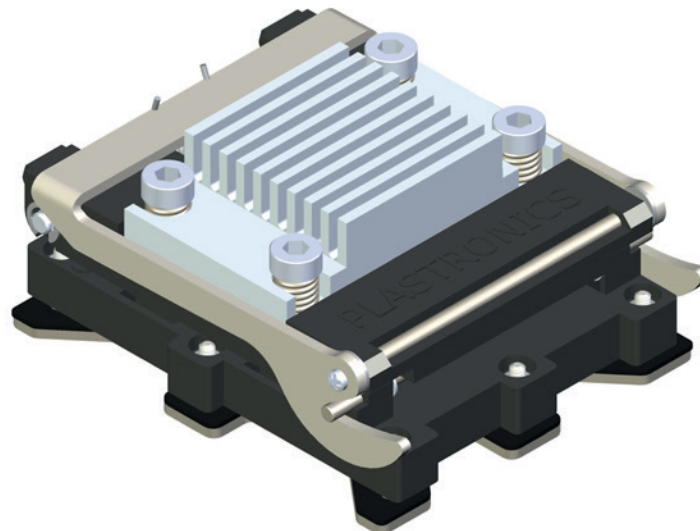
Materials

- Contact: BeCu/Au plated
- Spring: SS/Au plated
- Socket: Engineering plastics

Q-Series socket dimensions



Dimensions are in mm.



Heat sink, heater and RTD, spring-loaded pusher

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